

Title (en)

Probeless testing of pad buffers on a wafer

Title (de)

Kontaktlose Prüfung von Anschlusspuffern auf einem Wafer

Title (fr)

Essai sans contacts de tampons de connection dans un wafer

Publication

**EP 1431771 B1 20081231 (EN)**

Application

**EP 04100986 A 19980326**

Priority

- EP 98200962 A 19980326
- US 4172997 P 19970327
- US 4162197 P 19970327
- US 4161997 P 19970327

Abstract (en)

[origin: EP1431771A2] The peripheral circuitry (350, 360, ESD, BH) of an integrated circuit die on a wafer is tested without physically contacting the bond pads of the die. <IMAGE>

IPC 8 full level

**G06F 11/267** (2006.01); **G01R 31/317** (2006.01); **G01R 31/3185** (2006.01); **G11C 29/00** (2006.01); **G11C 29/48** (2006.01)

CPC (source: EP)

**G01R 31/31715** (2013.01); **G01R 31/318505** (2013.01); **G01R 31/318511** (2013.01); **G01R 31/318533** (2013.01); **G11C 29/006** (2013.01); **G11C 29/022** (2013.01); **G11C 29/48** (2013.01); **G11C 2029/3202** (2013.01)

Cited by

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Designated contracting state (EPC)

DE FR GB

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